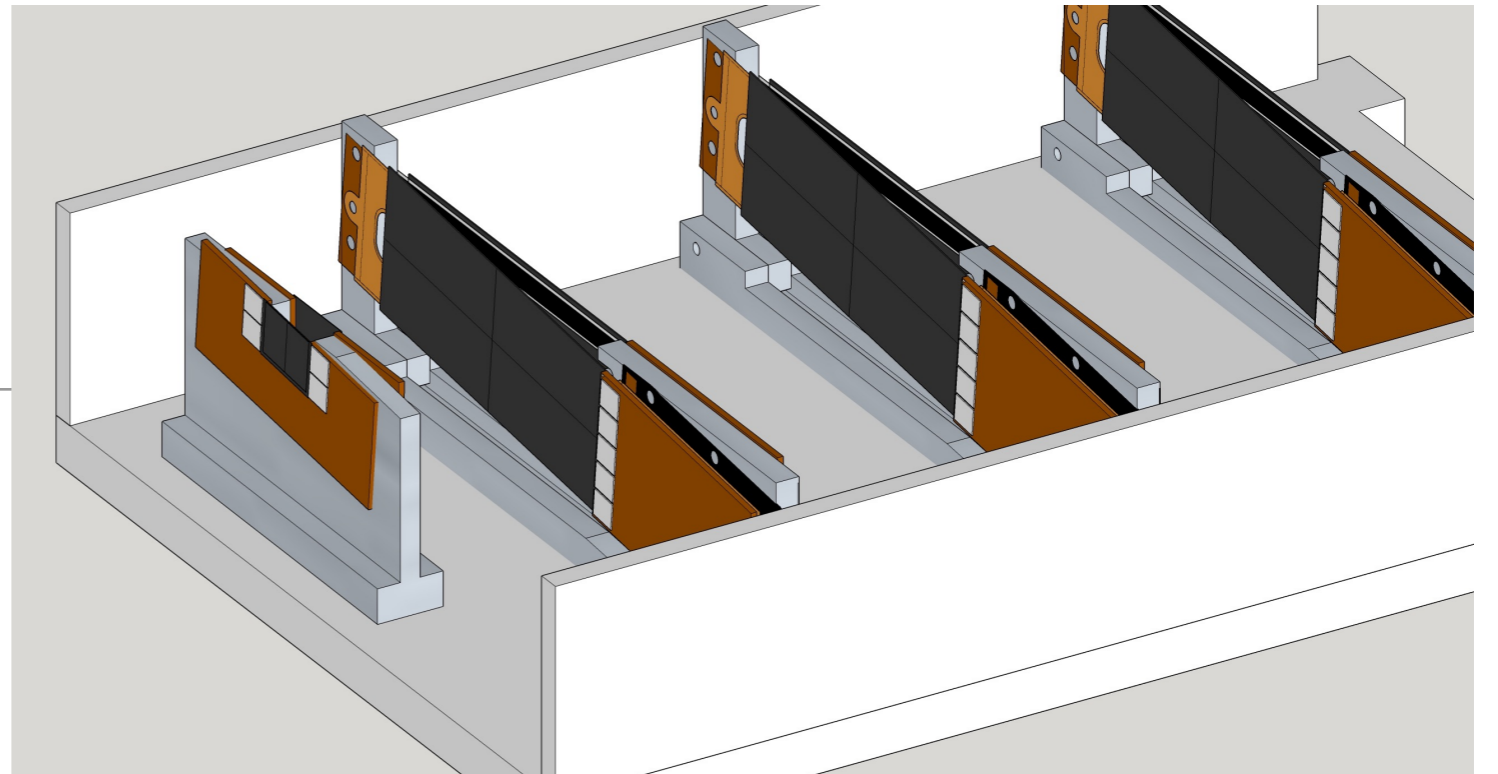


Upgrade Update

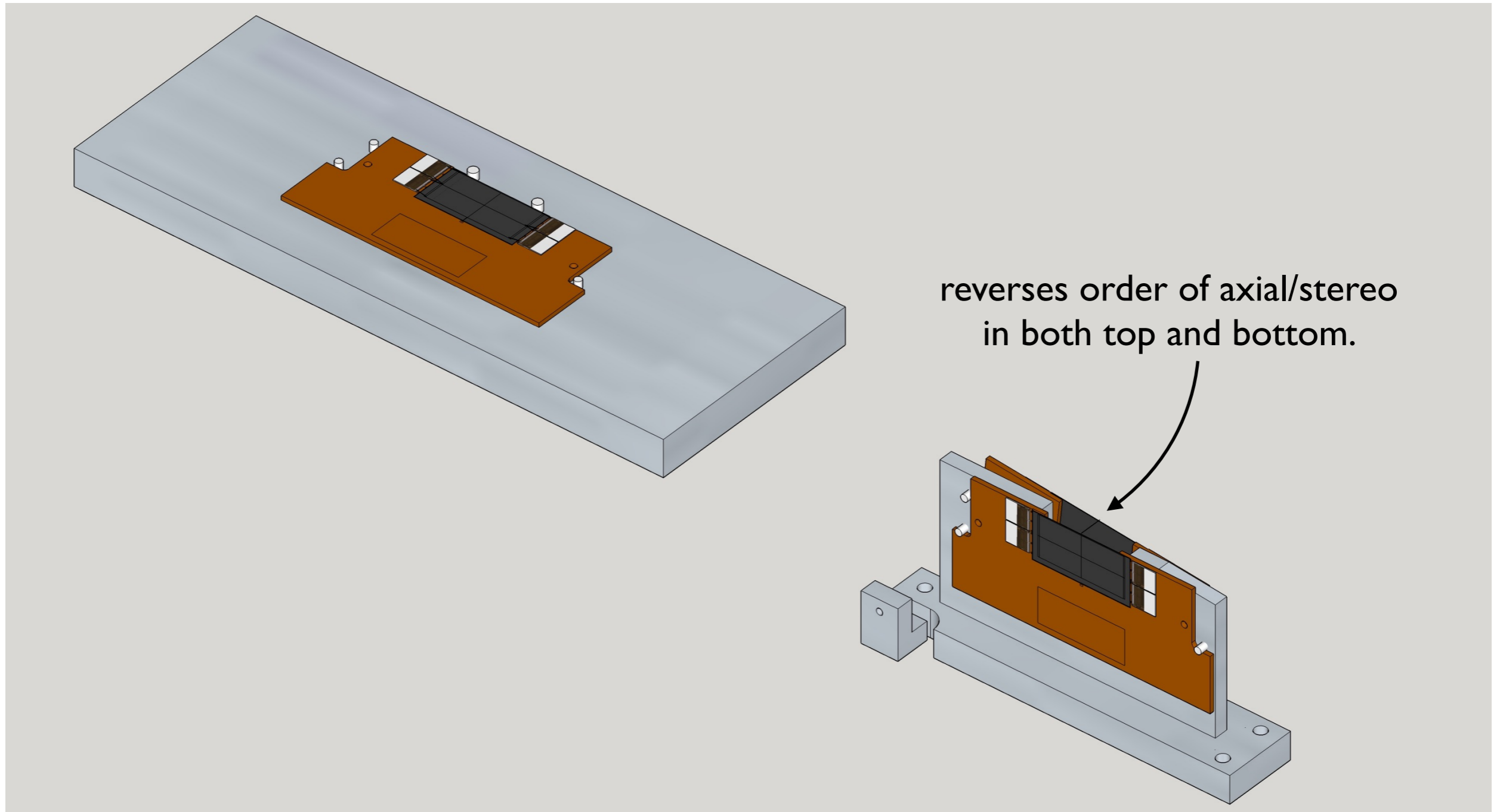
Tim Nelson - **SLAC**

Feb. 12, 2018

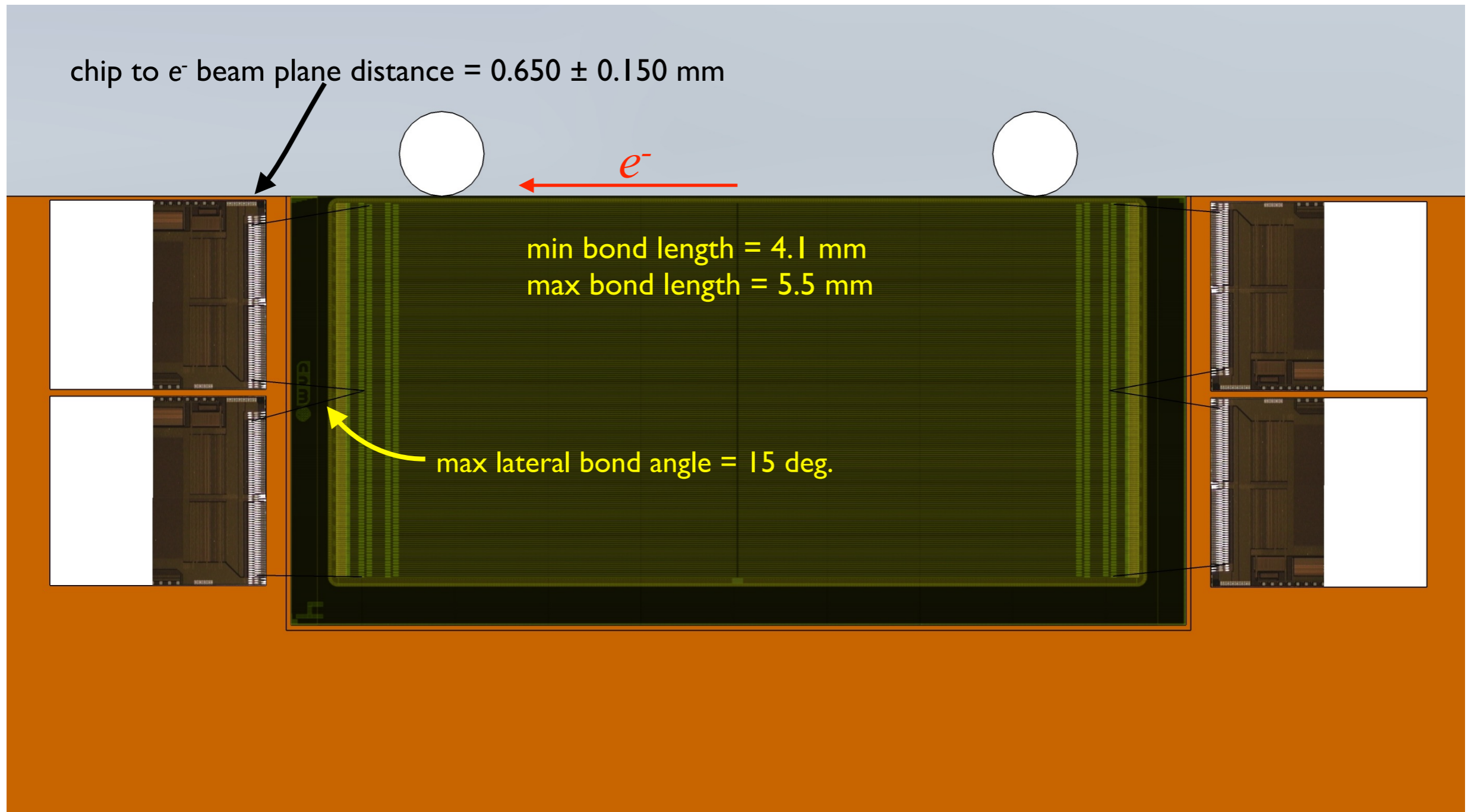


original conceptual design

Updated Design

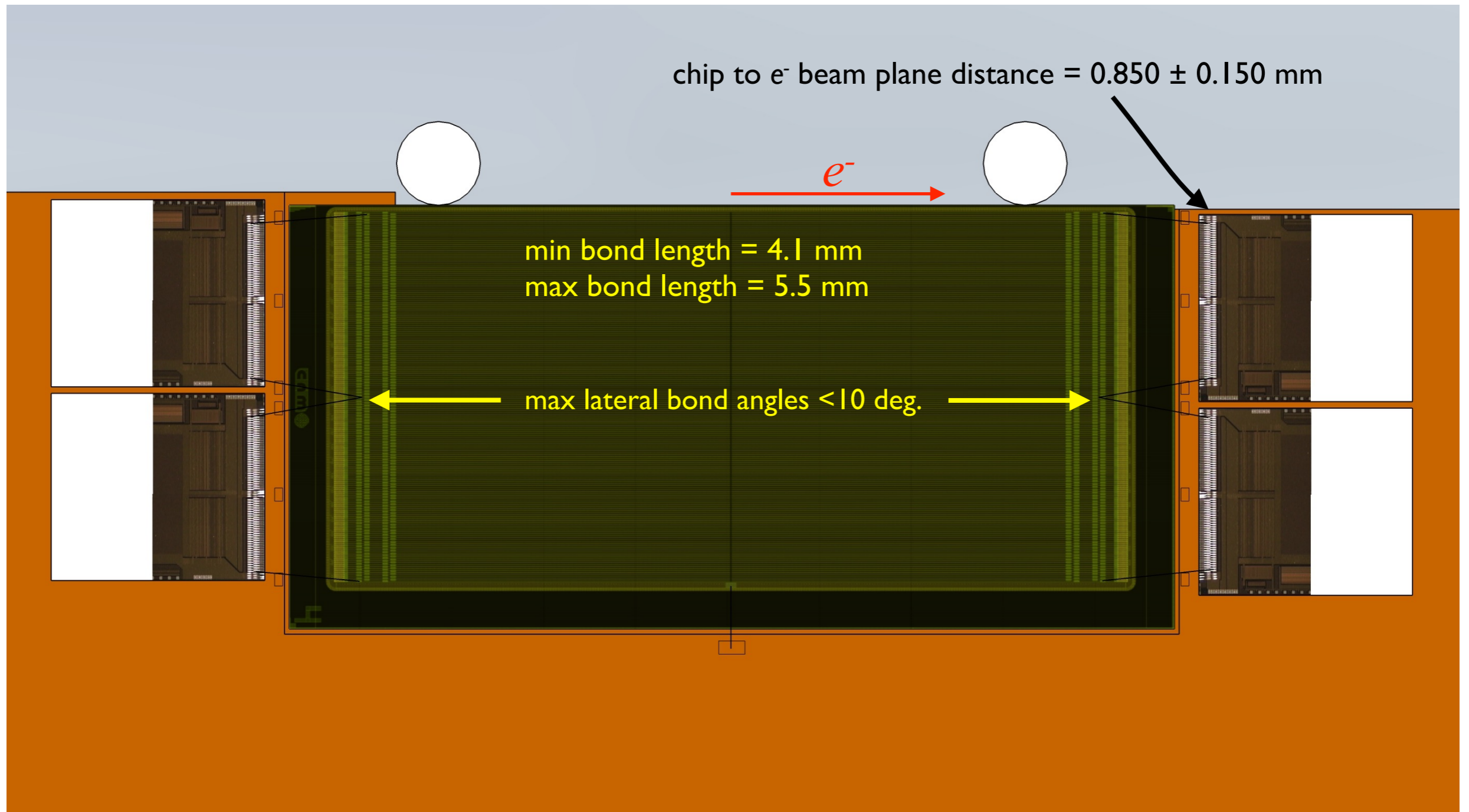


Initial Design with Final Sensor

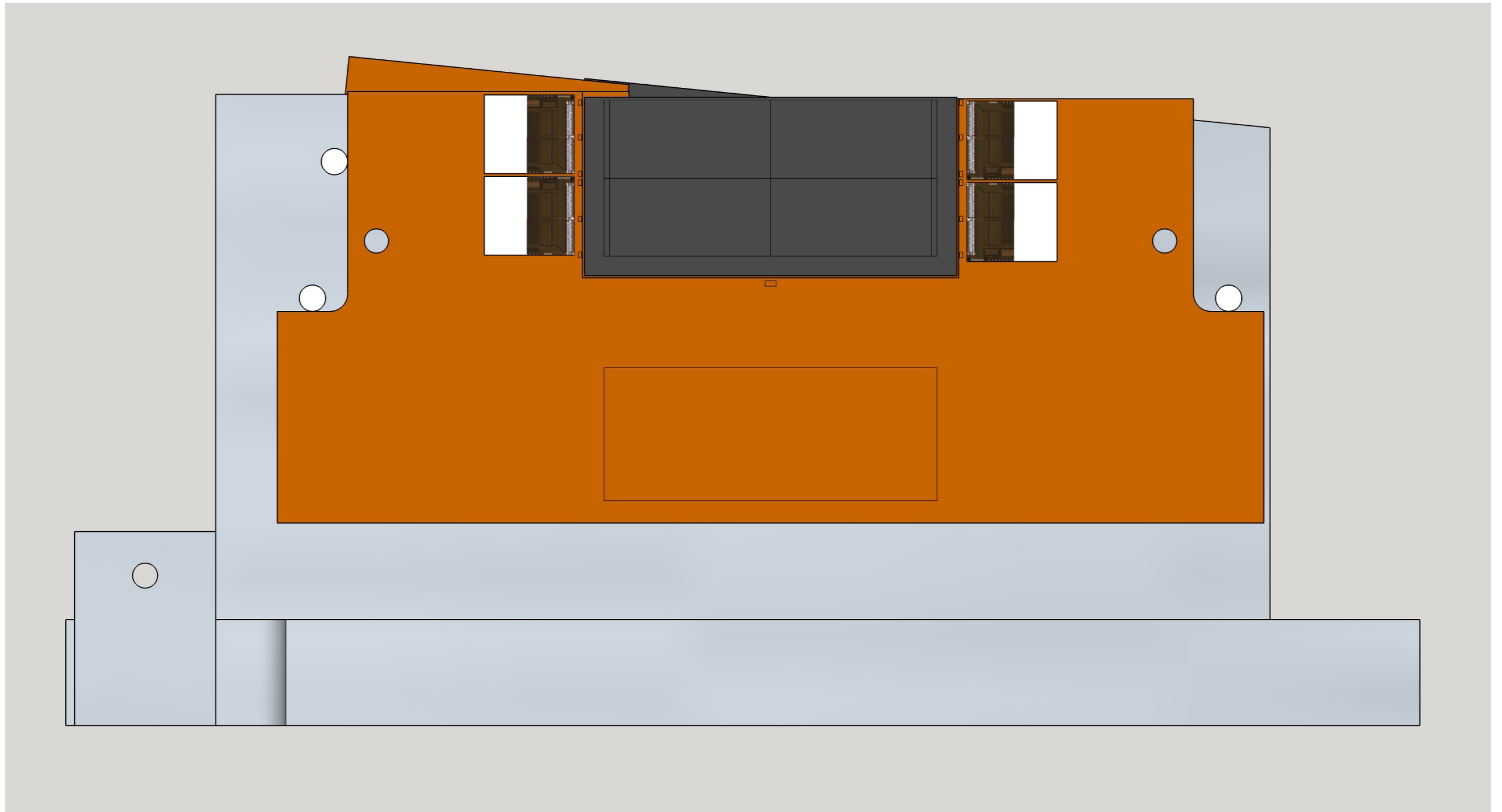


Updated Design

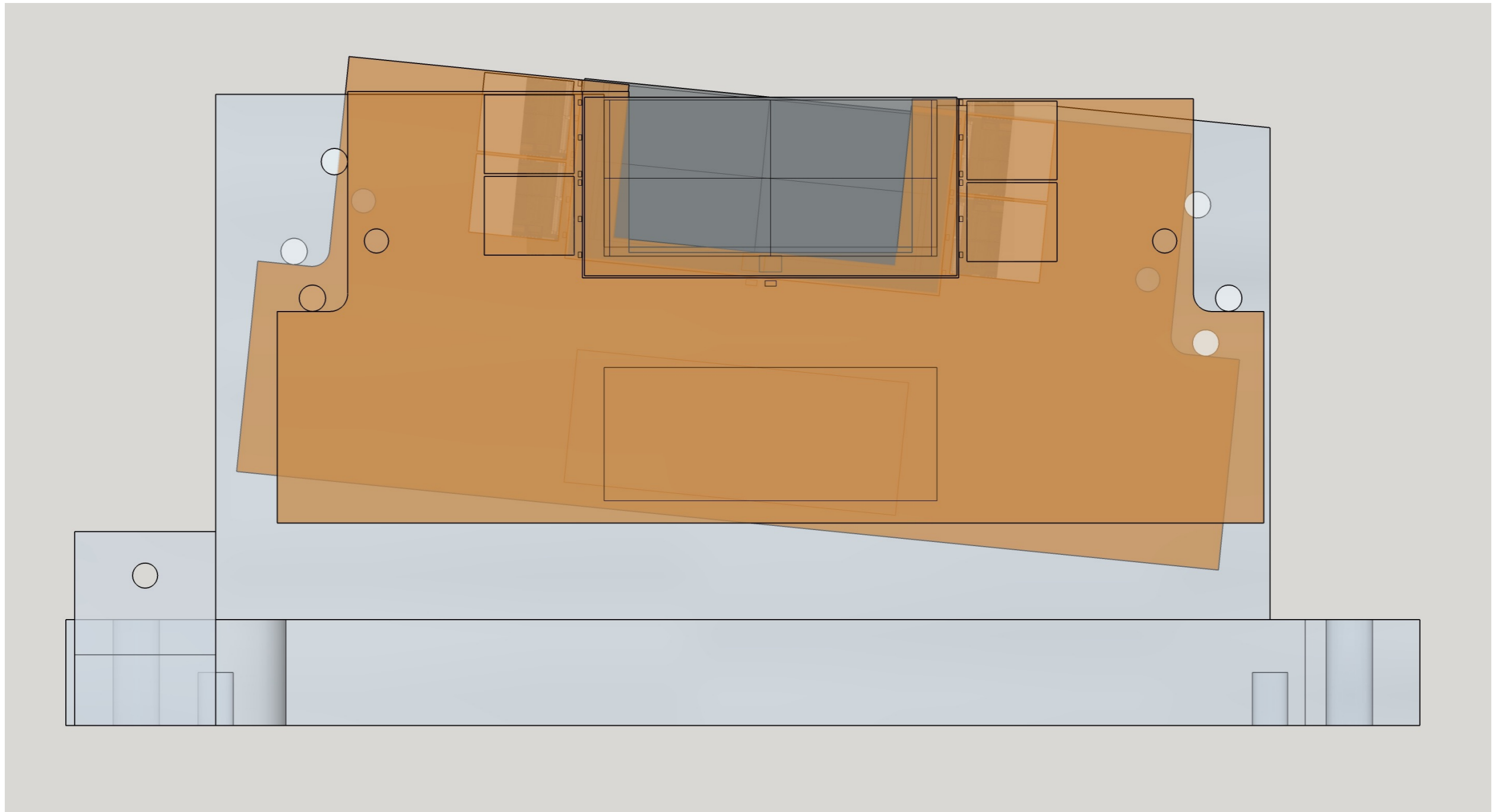
chip to e^- beam plane distance = 0.850 ± 0.150 mm



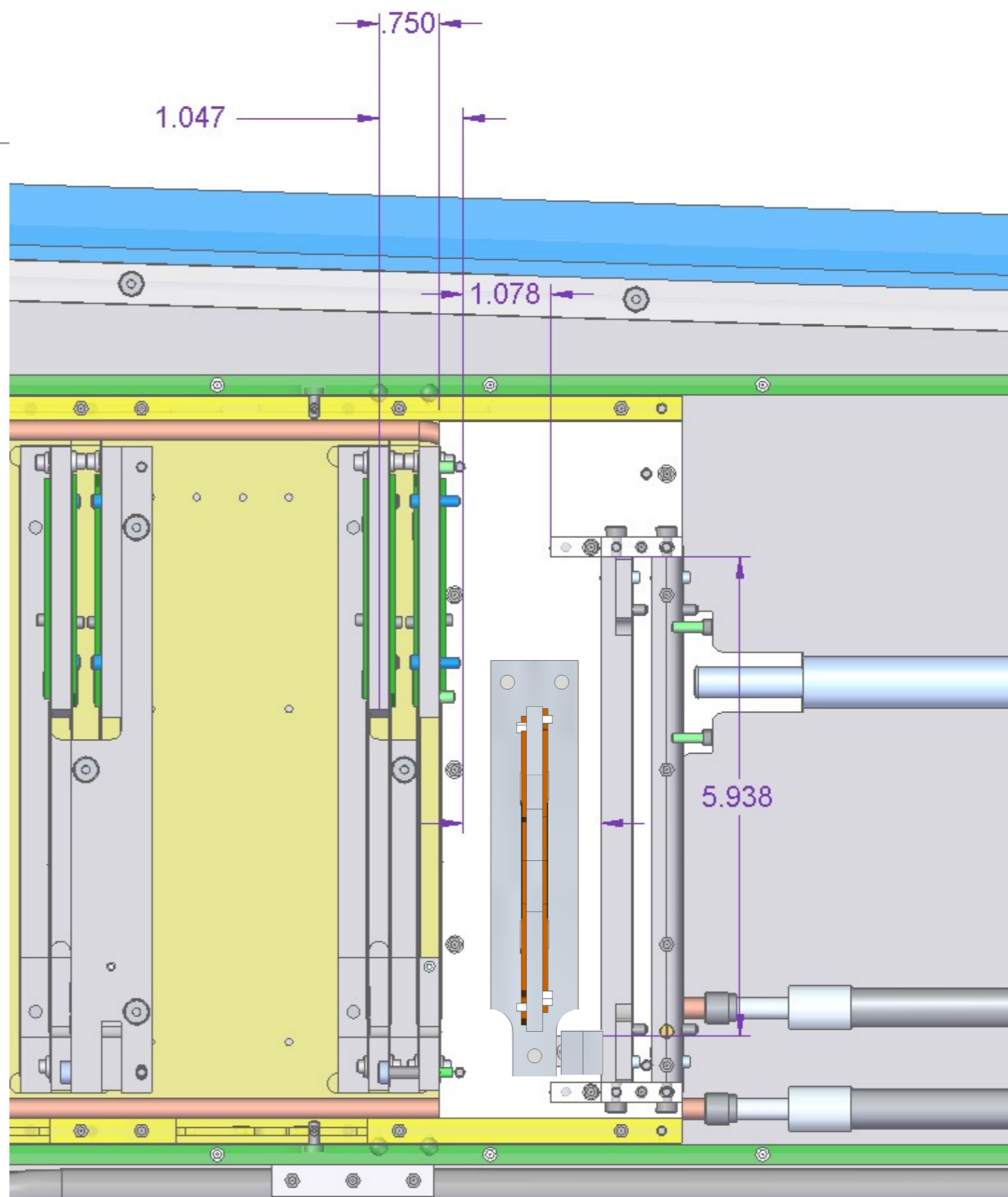
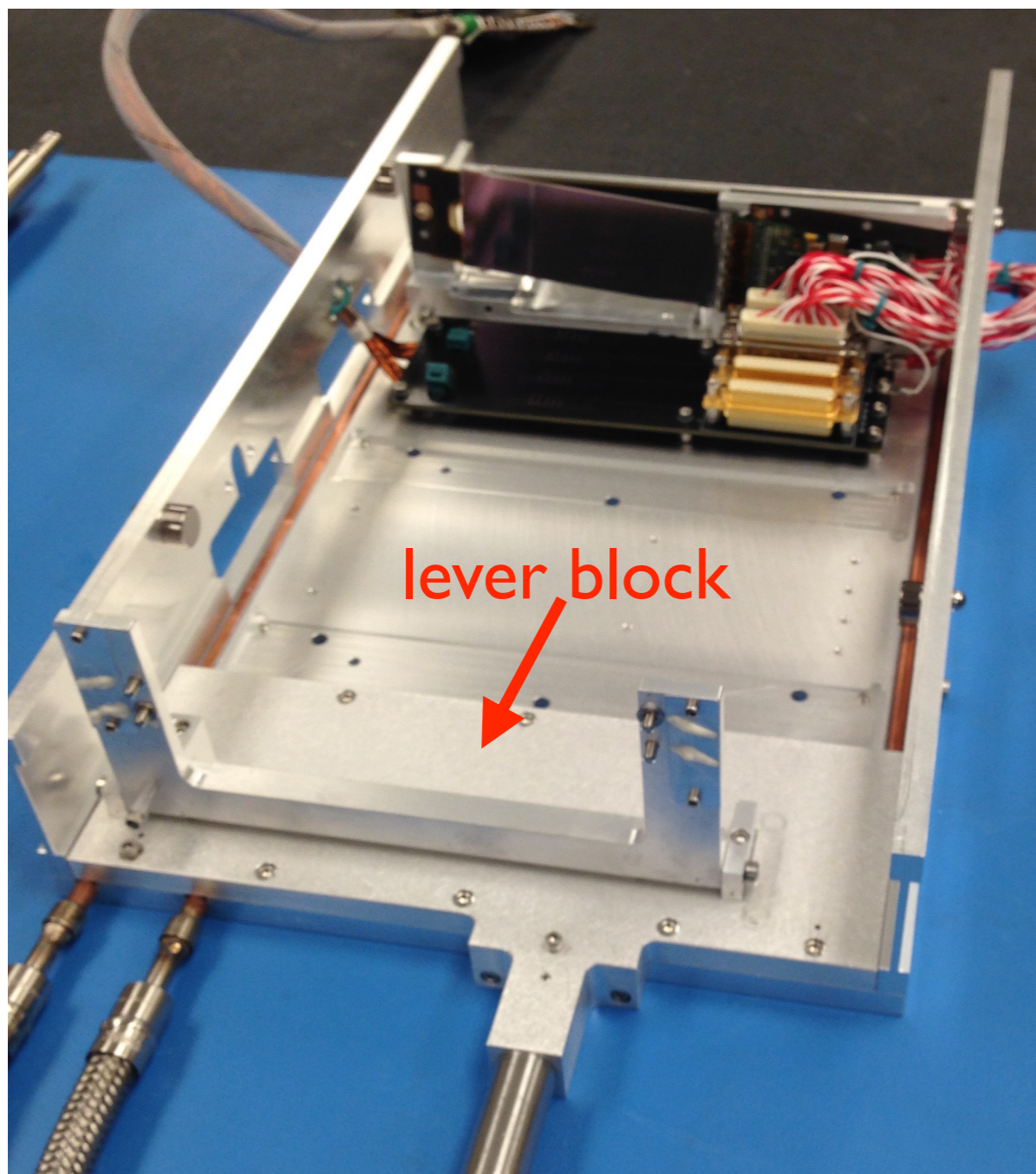
Updated Design



Updated Design



Updated Design



Next Steps

Have design reviewed by key players

- Forest Martinez-McKinney (UCSC wire bonding tech)
- Shawn Osier and Stephen boo (Mechanical Design)
- Tung Phan and Ryan Herbst (Hybrid Layout)

If all agree, have formal mechanical design and layout completed for review.